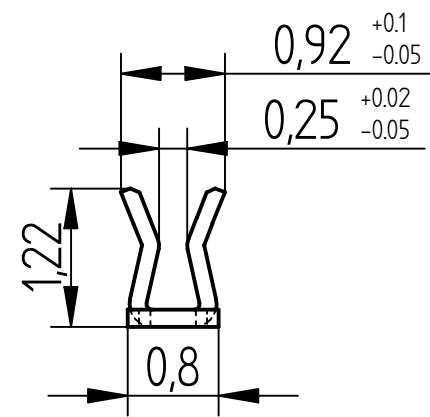
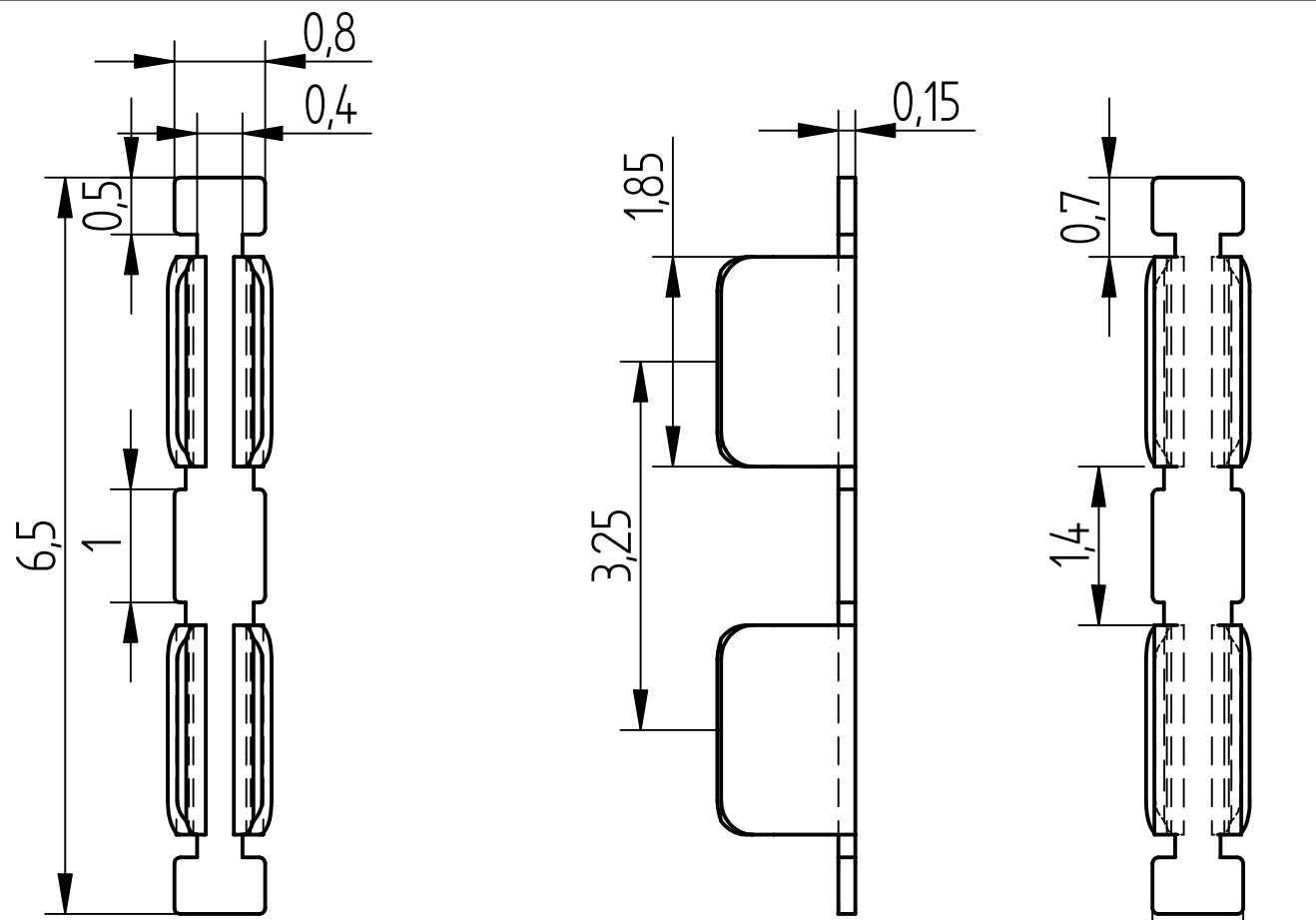
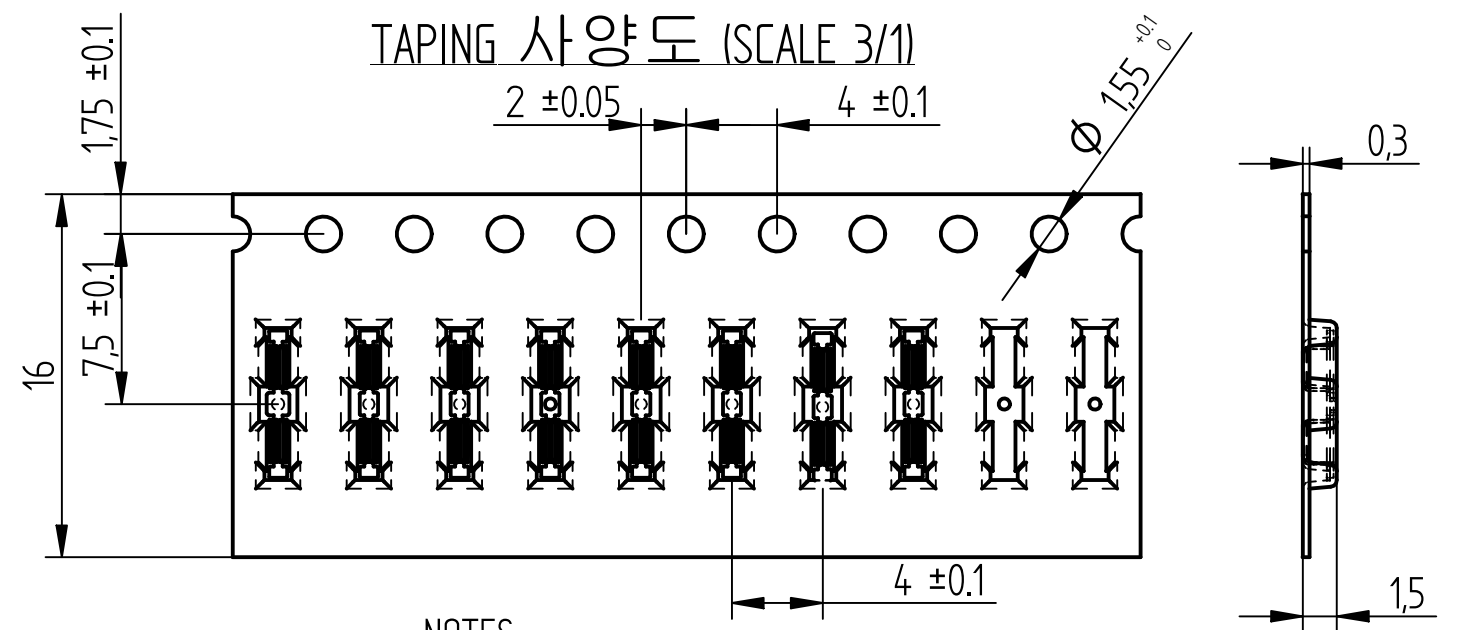
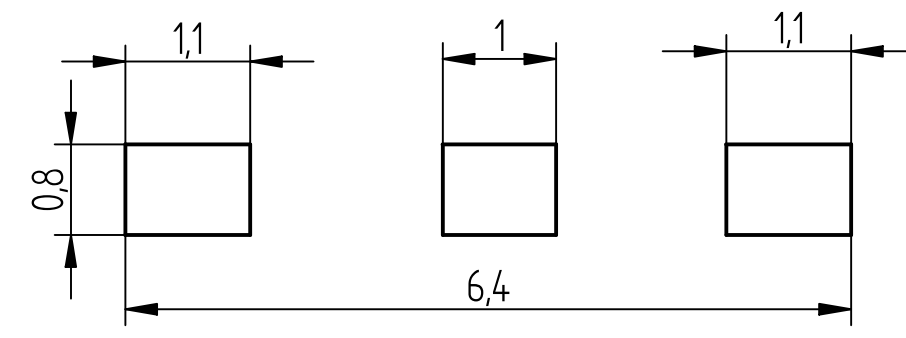
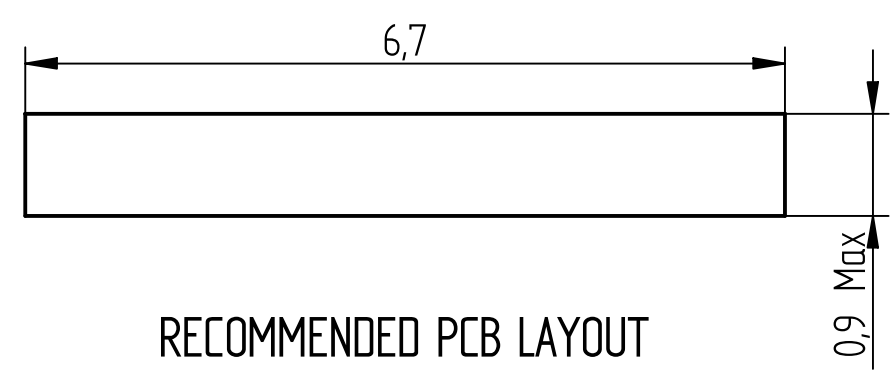


REVISION HISTORY			
REV	DESCRIPTION	DATE	APPROVED
A	신규 제정	2011.05.23	P.K.KOH
B	인이부 치수 변경 0.8 ⇒ 0.92mm	2011.06.09	P.K.KOH
C	SHIELD CASE THICKNESS 0.3±0.02 ⇒ 0.3 + 0.02 -0	2012.03.30	P.K.KOH




SCALE : 15/1



NOTES

- MATERIAL : SUS301
- MATERIAL THICKNESS : 0.15±
- FINISHED : Sn(100%) PLATING ON BOTH SIDE  
( NI 0.5µm Sn 1.27µm )
- PACKING MATERIALS.  
- REEL : HIPS 0.3±  
- COVER TAPE : PS  
- Q'TY/REEL : 10,000ea
- AVAILABLE SHIELD CASE THICKNESS : 0.3+ 0.02 -0
- CONTACT RESISTANCE 300mΩ MAX
- STENCIL THICKNESS : 0.12T
- Maintain 90°±3 while engage & disengage shield can & shield clip to prevent deformation & to maintain retention force of shield clip

APP.	DATA	NAME	 (주)이노칩테크놀로지	
CHECK	2011.05.23	LEE	TITLE	
DESIG.	2011.05.23	P.K.KOH	SHILED CLIP	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE ANGLES ± 0.3° 0~1 ± 0.05 1~5 ± 0.1 5 ~ 10 ± 0.15			SIZE	REV
			A3	C
FILE NAME: ICSRC6508-025SFR.dft			DWG NO	SCALE:
			ICSRC6508-025SFR	WEIGHT:
				SHEET 1 OF 1